

International Application No.: PCT/JP2005/009576
U.S. Patent Application No.: Unknown
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IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following new Abstract of the Disclosure:

ABSTRACT OF THE DISCLOSURE

A chip-mounted substrate includes a chip electronic component on a ceramic substrate having surface electrodes. The chip electronic component includes a ceramic sintered compact defining an element assembly and terminal electrodes. The surface electrodes of the ceramic substrate are integrated with the corresponding external terminal electrodes by sintering.